
2SK2408

Silicon N-Channel MOS FET

HITACHI

Application

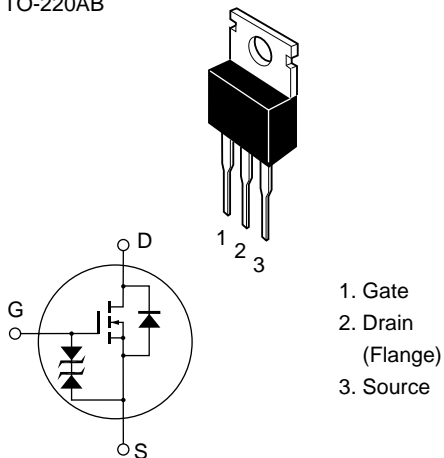
High speed power switching

Features

- Low on-resistance
- Built-in fast recovery diode ($t_{rr} = 120$ ns typ)
- High speed switching
- Low drive current
- Suitable for switching regulator, Motor control

Outline

TO-220AB



Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	500	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	I _D	7	A
Drain peak current	I _{D(pulse)} ^{*1}	28	A
Body to drain diode reverse drain current	I _{DR}	7	A
Channel dissipation	Pch ^{*2}	60	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	−55 to +150	°C

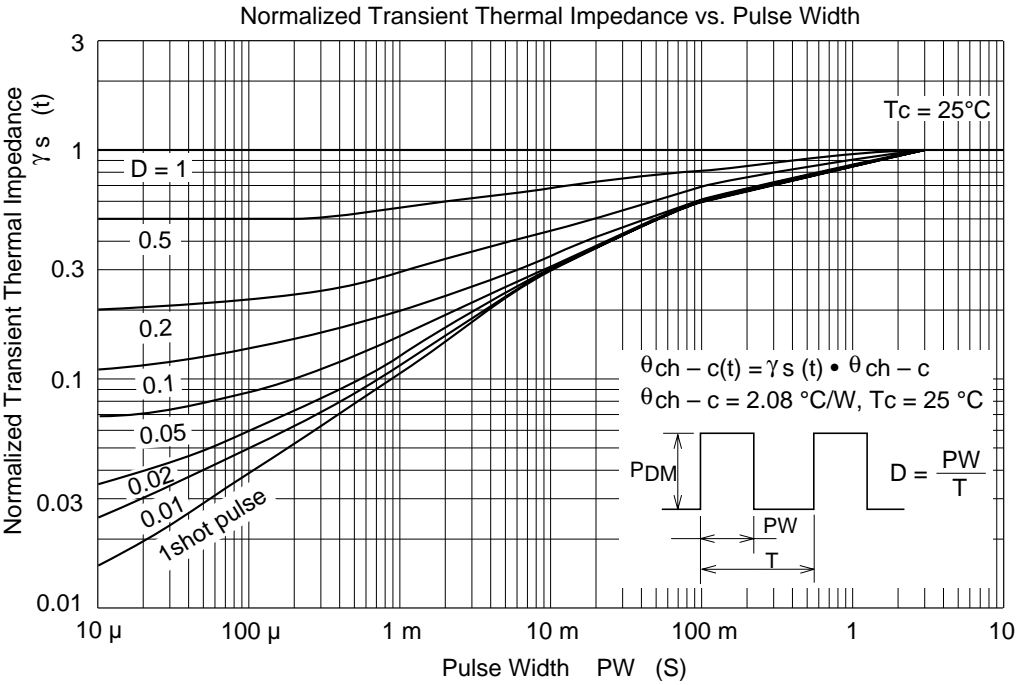
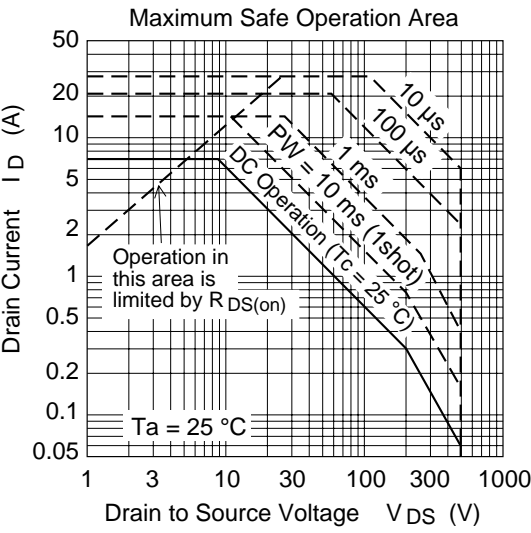
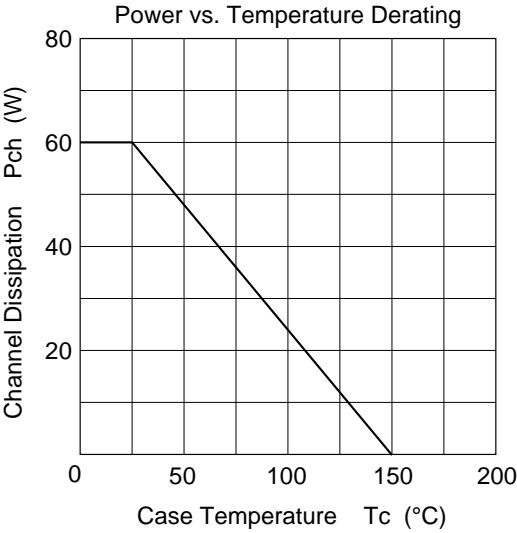
Notes 1. PW ≤ 10 μs, duty cycle ≤ 1 %
2. Value at Tc = 25 °C

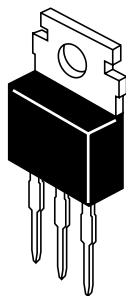
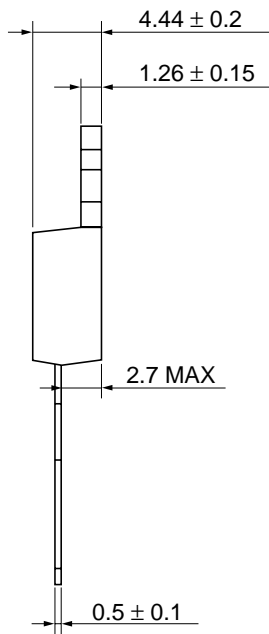
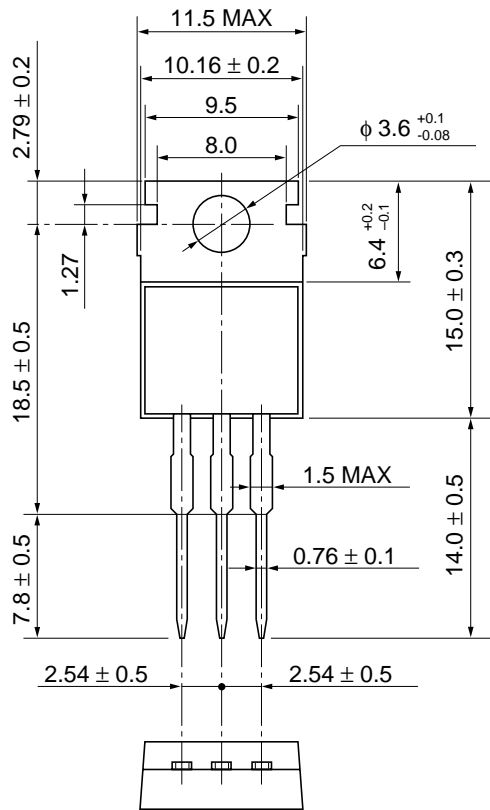
Electrical Characteristics ($T_a = 25^\circ\text{C}$)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	500	—	—	V	$I_D = 10\text{ mA}$, $V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	± 30	—	—	V	$I_G = \pm 100\text{ }\mu\text{A}$, $V_{DS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 25\text{ V}$, $V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	250	μA	$V_{DS} = 400\text{ V}$, $V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	—	3.0	V	$I_D = 1\text{ mA}$, $V_{DS} = 10\text{ V}$
Static drain to source on state resistance	$R_{DS(on)}$	—	0.7	0.9	Ω	$I_D = 4\text{ A}$ $V_{GS} = 10\text{ V}^{*1}$
Forward transfer admittance	$ y_{fs} $	3.5	6.0	—	S	$I_D = 4\text{ A}$ $V_{DS} = 10\text{ V}^{*1}$
Input capacitance	C_{iss}	—	1100	—	pF	$V_{DS} = 10\text{ V}$
Output capacitance	C_{oss}	—	310	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	C_{rss}	—	50	—	pF	$f = 1\text{ MHz}$
Turn-on delay time	$t_{d(on)}$	—	15	—	ns	$I_D = 4\text{ A}$
Rise time	t_r	—	55	—	ns	$V_{GS} = 10\text{ V}$
Turn-off delay time	$t_{d(off)}$	—	100	—	ns	$R_L = 7.5\text{ }\Omega$
Fall time	t_f	—	48	—	ns	
Body to drain diode forward voltage	V_{DF}	—	0.9	—	V	$I_F = 7\text{ A}$, $V_{GS} = 0$
Body to drain diode reverse recovery time	t_{rr}	—	120	—	ns	$I_F = 7\text{ A}$, $V_{GS} = 0$, $di_F / dt = 100\text{ A} / \mu\text{s}$

Note 1. Pulse Test

See characteristic curves of 2SK1516





Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.8 g

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Hitachi, Ltd.

Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL	NorthAmerica	: http://semiconductor.hitachi.com/
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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose, CA 95134 Tel: <1> (408) 433-1990 Fax: <1> (408) 433-0223	Hitachi Europe GmbH Electronic components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322
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Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building, No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX

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